

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A package assembly for an electronic device having edges, comprising:

a substrate having a first surface with a first plurality of contact pads and a second plurality of contact pads, a second surface with a plurality of connection pads, and a plurality of via holes connecting said first plurality of contact pads and said plurality of connection pads; and

a buffer layer between said substrate and said electronic device, and a surface of said electronic device having electrodes being opposite to said first surface of said substrate, said buffer layer having an opening to expose said first plurality of contact pads, wherein said buffer layer has a first part with a first density and a second part with a second density, said first density greater than said second density, wherein said second part of said buffer layer ~~surrounds~~seals the said edges of said electronic device and said first part of said buffer layer is configured with said electronic device such that said buffer layer functions as a self-planarization buffer between said electronic device and said substrate for increasing the hermeticity thereof.

2. (Previously Presented) The package assembly in claim 1, wherein said substrate is selected from the group consisting of an Al_2O_3 substrate, a ceramic substrate, a silicon substrate, a polymer substrate, and a glass substrate.

3. (Original) The package assembly in claim 1, wherein said buffer layer is selected from the group consisting of an organic film layer and a polymer film layer.

4-6. (Cancelled)

7. (Currently Amended) The package assembly in claim 1, further comprising a conductive layer formed on said electronic device ~~with respect to said lower surface~~and said buffer layer.

8. (Previously Presented) The package assembly in claim 1, wherein said first part has a relatively greater thickness and said second part has a relatively smaller thickness between 30-200 microns.

9. (Previously Presented) The package assembly in claim 1, wherein said first part is higher than said lower surface of said electronic device in altitude, contacted closely with said electronic device and disposed horizontally outside said electronic device.

10. (Cancelled)

11. (Original) The package assembly in claim 1, wherein said electronic device is a surface acoustic wave device.

12-21. (Cancelled)

22. (Currently Amended) A package assembly for an electronic device having edges and a lower surface having electrodes thereon, an upper surface and a vertical side with respect to said lower surface, comprising:

a substrate having a first surface with a first plurality of contact pads and a second plurality of contact pads, a second surface with a plurality of connection pads, and a plurality of via holes connecting said first plurality of contact pads and said plurality of connection pads; and

a buffer layer disposed on said substrate and having an opening to expose said first plurality of contact pads, wherein said buffer layer ~~further~~ is used for closely sealing said edges of said electronic device and further has a first part and a second part, said first part being lower than said upper surface of said electronic device and higher than said lower surface of said electronic device in altitude.

23. (Currently Amended) A package assembly for an electronic device having edges, a lower surface having electrodes thereon, an upper surface and a vertical side with respect to said lower surface, comprising:

a substrate having a first surface with a first plurality of contact pads and a second plurality of contact pads, a second surface with a plurality of connection pads, and a plurality of via holes connecting said first plurality of contact pads and said plurality of connection pads; and

a buffer layer disposed substantially between said substrate and said electronic device and having an opening to expose said first plurality of contact pads, wherein said buffer layer further forms a shoulder with a first surface disposed alongside said vertical side of said electronic device and being contacted closely with said vertical side and a second surface bearing said electronic device at said lower surface and being contacted closely with said lower surface, so as to closely seal said edges of said electronic device.

24. (Previously Presented) The package assembly for an electronic device according to claim 23, wherein said first surface being higher than said second surface in altitude and integrally formed with each other.

25. (Currently Amended) A package assembly for an electronic device having edges, a lower surface having electrodes thereon, an upper surface and a vertical side with respect to said lower surface, comprising:

a substrate having a first surface with a first plurality of contact pads and a second plurality of contact pads, a second surface with a plurality of connection pads, and a plurality of via holes connecting said first plurality of contact pads and said plurality of connection pads; and

a buffering means and a hermetical sealing means formed integrally, disposed substantially between said substrate and said electronic device and being contacted with ~~a corner~~said edges of said electronic device associated with said lower surface, wherein said hermetical sealing means is further contacted closely with said vertical side and said buffering means is further contacted closely with said lower surface.

26. (Currently Amended) A package assembly for an electronic device having a lower surface having electrodes thereon, comprising:

a substrate having a first surface with a first plurality of contact pads and a second plurality of contact pads, a second surface with a plurality of connection pads, and a plurality of via holes connecting said first plurality of contact pads and said plurality of connection pads; and

a buffer layer disposed substantially ~~between~~on said substrate and ~~said lower surface of said electronic device~~ and having an opening to expose said first plurality of contact pads, wherein said buffer layer has a first part with a first density and a second part with a second density greater than said first density, and is formed by being uniformly pressed downwardly by said lower surface of said electronic device.